

Quarterly Reliability Monitoring Results

Quarters: Q1/2021 to Q4/2021

Based on structural similarity

Supplier Nexperia B.V. Name of Laboratory		User Part Number PDZ5.1BGW Part Description												
										Nexperia DHAM	Zener			
								Assembly reliability labs		SMD package				
Based on AEC-Q101 Test		Test Conditions	Duration	# Lots	# Quantity	# Rejects								
	TEST													
	Pre- and Post-Stress													
# E1	Electrical Test	Tamb = 25 °C	N/A	see below	all parts	see below								
	PC	JESD22-A113 Bake Tamb = 125 °C Soak Tamb = 85 °C, RH = 85%	24 hours 168 hours											
# A1	Preconditioning	Reflow soldering	3 cycles	810	58300	0								
		MIL-STD-750-1 M1038 Method A Tj = Tjmax, Vr = 100% of max. datasheet												
# B1	Bias	reverse voltage	1000 hours	138	11040	0								
# B1b	SSOP Steady State Operational	MIL-STD-750-1 M1038 Method B Tj = Tjmax, Iz = 100% of max. datasheet reverse current	1000 hours	20	1600	0								
# BID	Steady State Operational	reverse current	1000 110015	20	1000	U								
# A4	TC Temperature Cycling	JESD22-A104 -65 °C to Tjmax, not to exceed 150°C	1000 cycles	170	13600	0								
# A2 alb	AC Autoclave	JESD22-A102 Tamb = 121 °C, RH = 100 % Pressure = 205 kPa (29.7 psia)	96 hours	170	13600	0								
# A3 alt	Adtociave	11essure = 205 ki a (25.7 psia)	96 Hours	170	13600	U								
# A2 alt	H3TRB High Humidity High Temperature Reverse Bias	JESD22-A101 Tamb = 85 °C, RH = 85%, VR = 80 % of rated reverse voltage ^[1]	1000 hours	170	13600	0								
	IOL	MIL-STD-750 Method 1037 ton = toff, devices powered to insure ΔTj =												
# A5	Intermittent Operating Life	100 °C for 15000 cycles	1000 hours	170	13600	0								
# C8	RSH Resistance to Solder Heat	JESD22-A111 260 °C ± 5 °C	10 s	130	3900	0								
# C10	SD Solderability	J-STD-002		363	3630	0								

^[1] The maximum applied voltage is limited by test chamber set up and does not exceed 115V.

Calculation of FIT and MTTF

Test considered for FIT calculation: High Temperature Reverse Bias (HTRB, Test #B1) Confidence level 60%, derated to 55 °C, activation energy 0.7 eV, test time 168 to 1000 hours

Wafer Fab	Technology	Quantity	Rejects	Failure Rate (FIT)	MTTF (hrs)
Nexperia					
DHAM	Zener	11040	0	0.38	2.60E+09

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